

M Z Abdullah

List of Publications by Year in descending order

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283
papers

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citations

125106

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287
all docs

287
docs citations

287
times ranked

3488
citing authors

#	ARTICLE	IF	CITATIONS
1	Effects of Blade Number on the Centrifugal Pump Performance: A Review. <i>Arabian Journal for Science and Engineering</i> , 2022, 47, 7945-7961.	1.7	9
2	Overview of the Important Factors Influencing the Performance of Eco-Friendly Brake Pads. <i>Polymers</i> , 2022, 14, 1180.	2.0	20
3	Heat transfer analysis on wafer annealing process in semiconductor multi-wafer furnace using CFD simulation. <i>Journal of Mechanical Science and Technology</i> , 2022, 36, 3143-3151.	0.7	2
4	Prediction of the void formation in no-flow underfill process using machine learning-based algorithm. <i>Microelectronics Reliability</i> , 2022, 135, 114586.	0.9	1
5	Numerical study on the influence of nozzle spray shape on spray characteristics using diesel and biofuel blends. <i>Biofuels</i> , 2021, 12, 1109-1121.	1.4	8
6	Heat transfer and deformation analysis of flexible printed circuit board under thermal and flow effects. <i>Circuit World</i> , 2021, 47, 213-221.	0.7	1
7	Mechanical reliability of self-aligned chip assembly after reflow soldering process. <i>Soldering and Surface Mount Technology</i> , 2021, 33, 9-17.	0.9	3
8	Design and Fabrication of a Dual Rotor-Embedded Wing Vertical Take-Off and Landing Unmanned Aerial Vehicle. <i>Unmanned Systems</i> , 2021, 09, 45-63.	2.7	7
9	Selected water thermal properties from molecular dynamics for engineering purposes. <i>Journal of Molecular Liquids</i> , 2021, 324, 114703.	2.3	15
10	Effect of volume concentration and nanofluid temperature on the thermal conductivity of mono and hybrid Al ₂ O ₃ -TiO ₂ nanofluid. <i>AIP Conference Proceedings</i> , 2021, , .	0.3	7
11	Study of Different Dispensing Patterns of No-Flow Underfill Using Numerical and Experimental Methods. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2021, 143, .	1.2	3
12	Correlating scalants characteristic and air bubbling rate in submerged vacuum membrane distillation: A fouling control strategy. <i>Journal of Membrane Science</i> , 2021, 621, 118991.	4.1	11
13	Investigations of Infrared Desktop Reflow Oven with FPCB Substrate during Reflow Soldering Process. <i>Metals</i> , 2021, 11, 1155.	1.0	12
14	Performance, combustion characteristics and economics analysis of a combined thermoelectric and thermophotovoltaic power system. <i>Applied Thermal Engineering</i> , 2021, 193, 117051.	3.0	5
15	Enhancement in Cathodic Redox Reactions of Single-Chambered Microbial Fuel Cells with Castor Oil-Emitted Powder as Cathode Material. <i>Materials</i> , 2021, 14, 4454.	1.3	6
16	Recent Advances on Thermally Conductive Adhesive in Electronic Packaging: A Review. <i>Polymers</i> , 2021, 13, 3337.	2.0	22
17	Die attachment, wire bonding, and encapsulation process in LED packaging: A review. <i>Sensors and Actuators A: Physical</i> , 2021, 329, 112817.	2.0	37
18	Optimization of flexible printed circuit board's cooling with air flow and thermal effects using response surface methodology. <i>Microelectronics International</i> , 2021, 38, 182-205.	0.4	3

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19	Double-Layer Micro Porous Media Burner from Lean to Rich Fuel Mixture: Analysis of Entropy Generation and Exergy Efficiency. <i>Entropy</i> , 2021, 23, 1663.	1.1	2
20	Design Optimization of Solid Rocket Propulsion: A Survey of Recent Advancements. <i>Journal of Spacecraft and Rockets</i> , 2020, 57, 3-11.	1.3	25
21	Effect of pin inclination angle on flow and heat transfer characteristics for a row of pins in a flow channel. <i>International Communications in Heat and Mass Transfer</i> , 2020, 110, 104396.	2.9	6
22	Effect of adhesive force on underfill process based on lattice Boltzmann method. <i>Microelectronics International</i> , 2020, 37, 54-63.	0.4	3
23	Experimental analysis on combustion characteristics of single layer porous media for various burner sizes. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 852, 012085.	0.3	0
24	Viscosity of Mono vs Hybrid Nanofluids: Measurement and Comparison. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 852, 012086.	0.3	1
25	Lead-free solder SAC 305 Volume Reduction and Cold Slump after Stencil Printing Process. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 852, 012084.	0.3	0
26	Entropy Generation and Exergy Analysis of Premixed Fuel-Air Combustion in Micro Porous Media Burner. <i>Entropy</i> , 2020, 22, 1104.	1.1	4
27	Thermophysical properties of Al ₂ O ₃ -CuO hybrid nanofluid at different nanoparticle mixture ratio: An experimental approach. <i>Journal of Molecular Liquids</i> , 2020, 313, 113458.	2.3	50
28	Three-dimensional CFD simulation of the stencil printing performance of solder paste. <i>International Journal of Advanced Manufacturing Technology</i> , 2020, 108, 3351-3359.	1.5	7
29	Metal oxide nanofluids in electronic cooling: a review. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 4381-4398.	1.1	43
30	Performance of Functionalized MWCNTs-Water Nanofluids for Heat Transfer Applications. <i>Arabian Journal for Science and Engineering</i> , 2020, 45, 5603-5614.	1.7	4
31	Study on the Addition of Nanoparticles in the Lead-free Solder During Reflow Soldering via Numerical Simulation - A Review. <i>CFD Letters</i> , 2020, 12, 111-119.	0.4	4
32	Effect of Contact Angle on Meniscus Evolution and Contact Line Jump of Underfill Fluid Flow in Flip-Chip Encapsulation. <i>CFD Letters</i> , 2020, 12, 28-38.	0.4	2
33	Symmetrical Unit-Cell Numerical Approach for Flip-Chip Underfill Flow Simulation. <i>CFD Letters</i> , 2020, 12, 55-63.	0.4	5
34	CAD-Based 3D Grain Burnback Analysis for Solid Rocket Motors. <i>Lecture Notes in Mechanical Engineering</i> , 2020, , 341-348.	0.3	0
35	Thermal Impact of Heat Spreader Co-Planarity to Electronic Packaging. <i>Journal of Advanced Research in Fluid Mechanics and Thermal Sciences</i> , 2020, 71, 1-9.	0.3	0
36	Heat Transfer Performance of a Synthetic Jet at Various Driving Frequencies and Diaphragm Amplitude. <i>Arabian Journal for Science and Engineering</i> , 2019, 44, 1043-1055.	1.7	6

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37	Development of foam porous media to undergo surface and submerged flame during premixed combustion. IOP Conference Series: Materials Science and Engineering, 2019, 505, 012123.	0.3	2
38	A novel analytical filling time chart for design optimization of flip-chip underfill encapsulation process. International Journal of Advanced Manufacturing Technology, 2019, 105, 3521-3530.	1.5	6
39	Numerical simulation of thermal fluid-structure interaction on flexible PCB in reflow soldering atmosphere. AIP Conference Proceedings, 2019, , .	0.3	0
40	Enhancement of nanofluid heat transfer in a mini-tube using SiO ₂ nanoparticles. Advances in Materials and Processing Technologies, 2019, 5, 607-616.	0.8	4
41	Thermal Analysis of a Cylindrical Sintered Wick Heat Pipe. Advanced Structured Materials, 2019, , 307-319.	0.3	0
42	Heat Transfer and Entropy Generation Abilities of MWCNTs/GNPs Hybrid Nanofluids in Microtubes. Entropy, 2019, 21, 480.	1.1	57
43	Experimental Investigation of Water-Cooled Heat Pipes in the Thermal Management of Lithium-Ion EV Batteries. Arabian Journal for Science and Engineering, 2019, 44, 7541-7552.	1.7	18
44	Comparative Study of Pressurized and Capillary Underfill Flow Using Lattice Boltzmann Method. Arabian Journal for Science and Engineering, 2019, 44, 7627-7652.	1.7	8
45	Stencil printing process performance on various aperture size and optimization for lead-free solder paste. International Journal of Advanced Manufacturing Technology, 2019, 102, 3369-3379.	1.5	15
46	Optimization of 3D IC stacking chip on molded encapsulation process: a response surface methodology approach. International Journal of Advanced Manufacturing Technology, 2019, 103, 1139-1153.	1.5	7
47	Numerical Analysis of Nozzle Flow and Spray Characteristics from Different Nozzles Using Diesel and Biofuel Blends. Energies, 2019, 12, 281.	1.6	28
48	Effect of Ultra-low Vegetable Oil Droplets on Microporous Media Burner Under Surface and Submerged Flames. Arabian Journal for Science and Engineering, 2019, 44, 5921-5935.	1.7	1
49	Influence of reaction layer thickness on surface/submerged flame during porous media combustion of micro burner. IOP Conference Series: Materials Science and Engineering, 2019, 508, 012072.	0.3	1
50	Finite Volume Method Study on Contact Line Jump Phenomena and Dynamic Contact Angle of Underfill Flow in Flip-Chip of Various Bump Pitches. IOP Conference Series: Materials Science and Engineering, 2019, 530, 012012.	0.3	5
51	Molecular dynamics simulation of the nano- reinforced lead-free solder at different reflow soldering process temperature. IOP Conference Series: Materials Science and Engineering, 2019, 701, 012014.	0.3	2
52	Filling efficiency of flip-chip underfill encapsulation process. Soldering and Surface Mount Technology, 2019, 32, 10-18.	0.9	13
53	Temperature Prediction on Flexible Printed Circuit Board in Reflow Oven Soldering for Motherboard Application. IOP Conference Series: Materials Science and Engineering, 2019, 530, 012019.	0.3	3
54	Nanofluid-filled heat pipes in managing the temperature of EV lithium-ion batteries. Journal of Physics: Conference Series, 2019, 1349, 012123.	0.3	12

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55	Numerical Study of Heat Transfer Enhancement Using Al ₂ O ₃ -Graphene/Water Hybrid Nanofluid Flow in Mini Tubes. Iranian Journal of Science and Technology, Transaction A: Science, 2019, 43, 1989-2000.	0.7	25
56	Effect of filling level and fillet profile on pin-through-hole solder joint. International Journal of Advanced Manufacturing Technology, 2019, 102, 1467-1485.	1.5	3
57	Study of velocity profiles of orbal biological system (OBS) using computational fluid dynamics (CFD). Journal of Computational Methods in Sciences and Engineering, 2019, 19, 447-454.	0.1	1
58	Study on convective heat transfer and pressure drop of MWCNTs/water nanofluid in mini-tube. Journal of Thermal Analysis and Calorimetry, 2019, 135, 123-132.	2.0	17
59	A Brief Survey of Preparation and Heat Transfer Enhancement of Hybrid Nanofluids. Strojinski Vestnik/Journal of Mechanical Engineering, 2019, , 441-453.	0.6	31
60	Flow Analysis Inside Coated Porous Media. Advanced Structured Materials, 2019, , 153-160.	0.3	1
61	NUMERICAL AND EXPERIMENTAL INVESTIGATIONS OF SPEAKER-DRIVEN SYNTHETIC JET ACTUATOR FOR ELECTRONICS COOLING APPLICATIONS. Heat Transfer Research, 2019, 50, 1369-1381.	0.9	3
62	Effect of Different S AC Based Nanoparticles Types on the Reflow Soldering Process of Miniaturized Component using Discrete Phase Model Simulation. Journal of Applied Fluid Mechanics, 2019, 12, 1683-1696.	0.4	3
63	Comparative study on porous media combustion characteristics using different discrete materials. MATEC Web of Conferences, 2018, 153, 01007.	0.1	4
64	Effect of scale size, orientation type and dispensing method on void formation in the CUF encapsulation of BGA. Sadhana - Academy Proceedings in Engineering Sciences, 2018, 43, 1.	0.8	10
65	Investigation on nano-reinforced solder paste after reflow soldering part 1: Effects of nano-reinforced solder paste on melting, hardness, spreading rate, and wetting quality. Microelectronics Reliability, 2018, 84, 230-237.	0.9	9
66	Effect of solder bump shapes on underfill flow in flip-chip encapsulation using analytical, numerical and PIV experimental approaches. Microelectronics Reliability, 2018, 81, 41-63.	0.9	26
67	Heat Transfer in a Loop Heat Pipe using Diamond-H ₂ O Nanofluid. Heat Transfer Engineering, 2018, 39, 1117-1131.	1.2	12
68	Investigation of micro burner performance during porous media combustion for surface and submerged flames. IOP Conference Series: Materials Science and Engineering, 2018, 370, 012049.	0.3	2
69	Flow Behavior Analysis of Emc in Molded Underfill (Muf) Encapsulation for Multi Flip-Chip Package. Journal of Physics: Conference Series, 2018, 1082, 012015.	0.3	2
70	Visualization of Underfill Flow in Ball Grid Array (BGA) using Particle Image Velocimetry (PIV). IOP Conference Series: Materials Science and Engineering, 2018, 370, 012064.	0.3	1
71	Effect of the gap height of radial gate on the volumetric flow rate in dam. IOP Conference Series: Materials Science and Engineering, 2018, 370, 012062.	0.3	6
72	Assessment of porous media combustion with foam porous media for surface/submerged flame. Materials Today: Proceedings, 2018, 5, 20865-20873.	0.9	9

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73	Numerical Investigation on the Effect of Squeegee Angle during Stencil Printing Process. Journal of Physics: Conference Series, 2018, 1082, 012057.	0.3	1
74	High-Speed Fractal Image Compression Featuring Deep Data Pipelining Strategy. IEEE Access, 2018, 6, 71389-71403.	2.6	8
75	Fluid/structure interaction study on the variation of radial gate's gap height in dam. IOP Conference Series: Materials Science and Engineering, 2018, 370, 012063.	0.3	11
76	Synthetic jet cooling diaphragm equation of motion characteristic and verification for computational fluid dynamic modelling. AIP Conference Proceedings, 2018, , .	0.3	1
77	Discrete Phase Model (DPM) study of nano-reinforced Lead Free Solder Sn-3.0Ag-0.5Cu (SAC305). IOP Conference Series: Materials Science and Engineering, 2018, 370, 012067.	0.3	1
78	Synthetic Jet Study on Resonance Driving Frequency for Electronic Cooling. , 2018, , 435-443.		0
79	A practical approach in porous medium combustion for domestic application: A review. IOP Conference Series: Materials Science and Engineering, 2018, 370, 012004.	0.3	8
80	Experiential study on temperature and emission performance of micro burner during porous media combustion. IOP Conference Series: Materials Science and Engineering, 2018, 370, 012057.	0.3	2
81	Characterization and Evaluation of PIV Illumination System Using High Power Light Emitting Diodes for WaterTank Applications. Instruments and Experimental Techniques, 2018, 61, 436-444.	0.1	0
82	EXPERIMENTAL INVESTIGATION ON THE HEAT TRANSFER PERFORMANCE OF HEAT PIPES IN COOLING HEV LITHIUM-ION BATTERIES. Heat Transfer Research, 2018, 49, 1745-1760.	0.9	4
83	EFFECT OF INCLINED ANGLE OF PIN ARRAYS ON FLOW AND HEAT TRANSFER CHARACTERISTICS IN FLOW CHANNEL. , 2018, , .		3
84	Optimization of operating conditions of heat pipes BTMS using response surface method. AIP Conference Proceedings, 2018, , .	0.3	0
85	Pengawalan Pertumbuhan Sebatian antara Logam Sambungan Pateri-Papan Litar Bercetak Menggunakan Salutan Nikel. Sains Malaysiana, 2018, 47, 2157-2162.	0.3	3
86	Effects of the preheat layer thickness on surface/submerged flame during porous media combustion of micro burner. Energy, 2017, 122, 103-110.	4.5	50
87	Assessment of porous media burner for surface/submerged flame during porous media combustion. AIP Conference Proceedings, 2017, , .	0.3	5
88	Heat transfer enhancement by flexible printed circuit board's deformation. International Communications in Heat and Mass Transfer, 2017, 84, 86-93.	2.9	7
89	Study on the Fluid-Structure Interaction at Different Layout of Stacked Chip in Molded Packaging. Arabian Journal for Science and Engineering, 2017, 42, 4743-4757.	1.7	4
90	Heat Transfer in a Loop Heat Pipe Using Fe ₂ NiO ₄ -H ₂ O Nanofluid. MATEC Web of Conferences, 2017, 109, 05001.	0.1	3

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91	Numerical simulation of fluid-structure interaction on flexible PCB with multiple ball grid array components. AIP Conference Proceedings, 2017, , .	0.3	2
92	Discrete phase method study of ball grid array underfill process using nano-silica filler-reinforced composite-encapsulant with varying filler loadings. Microelectronics Reliability, 2017, 72, 45-64.	0.9	25
93	The Effect of Freestream Flow Velocities on the Flexible Printed Circuit Board with Different BGA Package Arrangements. Arabian Journal for Science and Engineering, 2017, 42, 2075-2086.	1.7	4
94	A review of combustion-driven thermoelectric (TE) and thermophotovoltaic (TPV) power systems. Renewable and Sustainable Energy Reviews, 2017, 71, 572-584.	8.2	66
95	Heat transfer enhancement of LEDs with a combination of piezoelectric fans and a heat sink. Microelectronics Reliability, 2017, 68, 39-50.	0.9	31
96	Numerical simulation of self-alignment of chip resistor components for different silver content during reflow soldering. Microelectronics Reliability, 2017, 79, 69-78.	0.9	27
97	Experiment on forced convective heat transfer enhancement using MWCNTs/GNPs hybrid nanofluid and mini-tube. International Journal of Heat and Mass Transfer, 2017, 115, 1121-1131.	2.5	75
98	Influence of Material Properties on the Fluid-Structure Interaction aspects during Molded Underfill Process. MATEC Web of Conferences, 2017, 97, 01059.	0.1	8
99	Experimental and numerical investigation of flow and thermal effects on flexible printed circuit board. Microelectronics Reliability, 2017, 72, 5-17.	0.9	10
100	Discrete phase method particle simulation of ultra-fine package assembly with SAC305-TiO 2 nano-reinforced lead free solder at different weighted percentages. Microelectronics Reliability, 2017, 79, 336-351.	0.9	9
101	Molded underfill (MUF) encapsulation for flip-chip package: A numerical investigation. AIP Conference Proceedings, 2017, , .	0.3	3
102	CUF scaling effect on contact angle and threshold pressure. Soldering and Surface Mount Technology, 2017, 29, 173-190.	0.9	15
103	A study on thermoforming process of stretchable circuit and its performance in manufacturing of automotive lighting. AIP Conference Proceedings, 2017, , .	0.3	4
104	Comparative Study of the Scaling Effect on Pressure Profiles in Capillary Underfill Process. IOP Conference Series: Materials Science and Engineering, 2017, 203, 012012.	0.3	2
105	Scaling Effect on Velocity Profiles in Capillary Underfill Flow. IOP Conference Series: Materials Science and Engineering, 2017, 203, 012013.	0.3	1
106	Influence of low concentration of diamond water nanofluid in loop heat pipe. International Journal of Heat and Technology, 2017, 35, 539-548.	0.3	5
107	Effects of Aspect Ratio in Moulded Packaging Considering Fluid/Structure Interaction: A CFD Modelling Approach. Journal of Applied Fluid Mechanics, 2017, 10, 1799-1811.	0.4	5
108	LIFE CYCLE ASSESSMENT OF TOXICITY POTENTIAL OF METALLIC ELEMENTS AND PROCESS STAGES IN ELECTRONICS: A CASE STUDY OF ELECTRONIC CONNECTOR LEADS. Environmental Engineering and Management Journal, 2017, 16, 1521-1530.	0.2	0

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109	Unsteady Pressure Distribution of a Flapping Wing Undergoing Root Flapping Motion with Elbow Joint at Different Reduced Frequencies. <i>International Review of Aerospace Engineering</i> , 2017, 10, 105.	0.2	0
110	APPLYING NUMERICAL METHOD IN IMPROVING EMERGENCY GATE DESIGN OF MENGGUANG DAM. <i>Advances and Applications in Fluid Mechanics</i> , 2017, 20, 353-362.	0.1	0
111	Influence of printed circuit board thickness in wave soldering. <i>Scientia Iranica</i> , 2017, .	0.3	6
112	Compact Multislot Planar Monopole Antenna for Microwave Imaging. <i>Advanced Science Letters</i> , 2017, 23, 11031-11034.	0.2	0
113	Lattice Boltzmann Model of 3D Multiphase Flow in Artery Bifurcation Aneurysm Problem. <i>Computational and Mathematical Methods in Medicine</i> , 2016, 2016, 1-17.	0.7	8
114	Detection of Cracks in Concrete Structure Using Microwave Imaging Technique. <i>International Journal of Microwave Science and Technology</i> , 2016, 2016, 1-6.	0.6	7
115	Improvement of Porous Porcelain through Glaze Coating. <i>Materials Science Forum</i> , 2016, 840, 19-23.	0.3	0
116	Effect of thermocapillary action in the underfill encapsulation of multi-stack ball grid array. <i>Microelectronics Reliability</i> , 2016, 66, 143-160.	0.9	22
117	Comparative assessment of a porous burner using vegetable cooking oil"kerosene fuel blends for thermoelectric and thermophotovoltaic power generation. <i>Fuel</i> , 2016, 180, 137-147.	3.4	14
118	High-speed implementation of fractal image compression in low cost FPGA. <i>Microprocessors and Microsystems</i> , 2016, 47, 429-440.	1.8	13
119	Effect of ILU dispensing types for different solder bump arrangements on CUF encapsulation process. <i>Microelectronic Engineering</i> , 2016, 163, 83-97.	1.1	26
120	Lattice Boltzmann method study of effect three dimensional stacking-chip package layout on micro-void formation during encapsulation process. <i>Microelectronics Reliability</i> , 2016, 65, 205-216.	0.9	15
121	Real-time implementation of Fractal Image Compression in low cost FPGA. , 2016, , .		4
122	FVM based simulation on multi-stack ball grid array (BGA). <i>AIP Conference Proceedings</i> , 2016, , .	0.3	0
123	Hardness profiles of Sn-3.0Ag-0.5Cu-TiO ₂ composite solder by nanoindentation. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2016, 669, 178-186.	2.6	28
124	Backward Compatibility Solder Joint Formation at High Peak Reflow Temperature for Aerospace Applications. <i>Arabian Journal for Science and Engineering</i> , 2016, 41, 1813-1823.	1.1	4
125	Effect of Wing Deformation on the Aerodynamic Performance of Flapping Wings: Fluid-Structure Interaction Approach. <i>Journal of Aerospace Engineering</i> , 2016, 29, .	0.8	13
126	Microstructure and mechanical properties of Pb-free Sn"3.0Ag"0.5Cu solder pastes added with NiO nanoparticles after reflow soldering process. <i>Materials and Design</i> , 2016, 90, 499-507.	3.3	65

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127	Finite volume-based simulation of the wave soldering process: Influence of the conveyor angle on pin-through-hole capillary flow. Numerical Heat Transfer; Part A: Applications, 2016, 69, 295-310.	1.2	13
128	Lattice Boltzmann method study of bga bump arrangements on void formation. Microelectronics Reliability, 2016, 56, 170-181.	0.9	29
129	Numerical Investigation on the Effect of Pressure and Temperature on the Melt Filling During Injection Molding Process. Arabian Journal for Science and Engineering, 2016, 41, 1907-1919.	1.1	10
130	Thermo-mechanical challenges of reflowed lead-free solder joints in surface mount components: a review. Soldering and Surface Mount Technology, 2016, 28, 41-62.	0.9	47
131	Physical, mechanical, and thermal properties improvement of porous alumina substrate through dip-coating and re-sintering procedures. Ceramics International, 2016, 42, 7717-7729.	2.3	10
132	Single-phase heat transfer enhancement in micro/minichannels using nanofluids: Theory and applications. Applied Energy, 2016, 164, 733-755.	5.1	125
133	Effect of ceramic coating in combustion and cogeneration performance of Al ₂ O ₃ porous medium. Journal of the Energy Institute, 2016, 89, 81-93.	2.7	21
134	Lattice Boltzmann Method of Different BGA Orientations on I-Type Dispensing Method. PLoS ONE, 2016, 11, e0159357.	1.1	14
135	Effects of Temperature on the Wave Soldering of Printed Circuit Boards: CFD Modeling Approach. Journal of Applied Fluid Mechanics, 2016, 9, 2053-2062.	0.4	6
136	Thermal fluid-structure interaction of PCB configurations during the wave soldering process. Soldering and Surface Mount Technology, 2015, 27, 31-44.	0.9	12
137	Piezoresistive effects in controllable defective HFTCVD graphene-based flexible pressure sensor. Scientific Reports, 2015, 5, 14751.	1.6	53
138	A computational fluid dynamics analysis of the wave soldering process. International Journal of Numerical Methods for Heat and Fluid Flow, 2015, 25, 1231-1247.	1.6	3
139	Oxygen Uptake by Biological Processes inside Oxidation Ditch. Applied Mechanics and Materials, 2015, 802, 490-495.	0.2	0
140	Experimental analysis and FEM simulation of loop heat charged with diamond nanofluid for desktop PC cooling. IOP Conference Series: Materials Science and Engineering, 2015, 88, 012038.	0.3	3
141	Combustion Characteristics of Butane Porous Burner for Thermoelectric Power Generation. Journal of Combustion, 2015, 2015, 1-13.	0.5	5
142	Characteristic Airflow Patterns During Inspiration and Expiration: Experimental and Numerical Investigation. Journal of Medical and Biological Engineering, 2015, 35, 387-394.	1.0	11
143	Optimization of SiO ₂ nanoparticle mass concentration and heat input on a loop heat pipe. Case Studies in Thermal Engineering, 2015, 6, 238-250.	2.8	21
144	Numerical investigations on the effects of different cooling periods in reflow-soldering process. Heat and Mass Transfer, 2015, 51, 1413-1423.	1.2	17

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145	Effects of diamond nanoparticles reinforcement into lead-free Sn ^{3.0} Ag ^{0.5} Cu solder pastes on microstructure and mechanical properties after reflow soldering process. <i>Materials and Design</i> , 2015, 82, 206-215.	3.3	54
146	Optimization of pin through hole connector in thermal fluid-structure interaction analysis of wave soldering process using response surface methodology. <i>Simulation Modelling Practice and Theory</i> , 2015, 57, 45-57.	2.2	16
147	Experimental analysis of a porous burner operating on kerosene-vegetable cooking oil blends for thermophotovoltaic power generation. <i>Energy Conversion and Management</i> , 2015, 96, 544-560.	4.4	18
148	Experimental and numerical investigation of 3D gas flow temperature field in infrared heating reflow oven with circulating fan. <i>International Journal of Heat and Mass Transfer</i> , 2015, 87, 49-58.	2.5	43
149	Reflow Optimization Process: Thermal Stress Using Numerical Analysis and Intermetallic Spallation in Backwards Compatibility Solder Joints. <i>Arabian Journal for Science and Engineering</i> , 2015, 40, 1669-1679.	1.1	9
150	Effect of Skin Flexibility on Aerodynamic Performance of Flexible Skin Flapping Wings for Micro Air Vehicles. <i>Experimental Techniques</i> , 2015, 39, 11-20.	0.9	9
151	Centrifuge and storage precipitation of TiO ₂ nanoparticles by the sol-gel method. <i>Journal of Alloys and Compounds</i> , 2015, 651, 557-564.	2.8	20
152	Effects of PCB thickness on adjustable fountain wave soldering. <i>Sadhana - Academy Proceedings in Engineering Sciences</i> , 2015, 40, 2197-2220.	0.8	5
153	Effects of Fe ₂ NiO ₄ nanoparticles addition into lead free Sn ^{3.0} Ag ^{0.5} Cu solder pastes on microstructure and mechanical properties after reflow soldering process. <i>Materials & Design</i> , 2015, 67, 197-208.	5.1	51
154	Experimental investigation of the performance of a liquid fuel-fired porous burner operating on kerosene-vegetable cooking oil (VCO) blends for micro-cogeneration of thermoelectric power. <i>Renewable Energy</i> , 2015, 74, 505-516.	4.3	17
155	LIFT PERFORMANCE OF A CAMBERED WING FOR AERODYNAMIC PERFORMANCE ENHANCEMENT OF THE FLAPPING WING. <i>Jurnal Teknologi (Sciences and Engineering)</i> , 2015, 75, .	0.3	0
156	Effects of Solder Temperature on Pin Through-Hole during Wave Soldering: Thermal-Fluid Structure Interaction Analysis. <i>Scientific World Journal, The</i> , 2014, 2014, 1-13.	0.8	6
157	The Effect of Morphing Force on Aerodynamic Performances of TM Wing. <i>Advanced Materials Research</i> , 2014, 980, 102-106.	0.3	0
158	Analytical Comparisons of Standardized Nasal Cavity. <i>Journal of Medical Imaging and Health Informatics</i> , 2014, 4, 14-20.	0.2	5
159	Applications of Porous Media Combustion Technology. , 2014, , 615-633.		9
160	Experimental Study on the Effect of Skin Flexibility on Aerodynamic Performance of Flapping Wings for Micro Air Vehicles. <i>Applied Mechanics and Materials</i> , 2014, 629, 18-23.	0.2	2
161	Effect of piezoelectric fan mode shape on the heat transfer characteristics. <i>International Communications in Heat and Mass Transfer</i> , 2014, 52, 140-151.	2.9	36
162	Implications of Adjustable Fountain Wave in Pin Through Hole Soldering Process. <i>Arabian Journal for Science and Engineering</i> , 2014, 39, 9101-9111.	1.1	5

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